

SMD METALLIZED FILM-OVER-FOAM GROUNDING CONTACT

Laird's SMD (Surface Mount Device) Grounding Contact is a foam cored contact with a metallized polyimide film outer covering. It is used for circuit grounding of SMT (Surface Mount Technology) devices. These contacts are designed to be solder reflow compatible, and are suitable for automatic processing.

FEATURES

- Sn / Cu Plated PI Film outer layer
- Polymeric Foam Core
- Soft SMD contacts are RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Reflow tunnel compatible to 260° C
- Patent Pending
- UL94 HB Flammability Rating

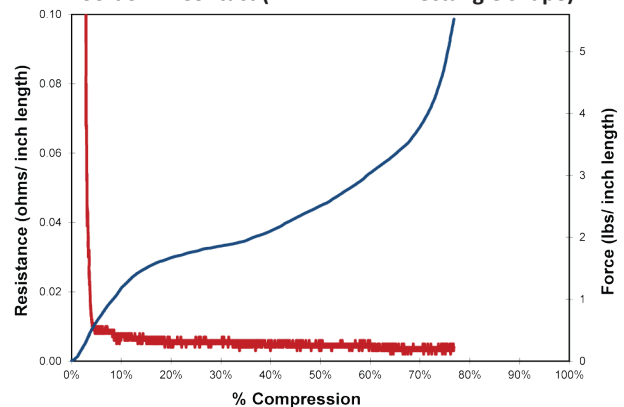
MARKETS

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Automotive
- Laptop computers and tablets
- Networking equipment
- Desktop computers
- Telecommunications cabinets

| Item | Unit | Value | Test Method |
|--|-----------|-----------------------------|-------------------|
| Z-Axis Resistance | | | Laird Internal |
| Before Reflow | Ω | <0.06 | |
| After Reflow | Ω | <0.10 | |
| Flammability | | PASS | UL 94 HB* |
| Solder Adhesion Strength (Contact to PCB) | kgf | >0.8 | Laird Internal |
| Hardness (Shore A) | durometer | <20 | ASTM D 2240 |
| Compression Set | % | <15 | ASTM D3574 Test D |
| Operation Temperature | °C | -40° to 70° | |
| Restricted Substances | | RoHS Compliant Halogen Free | |

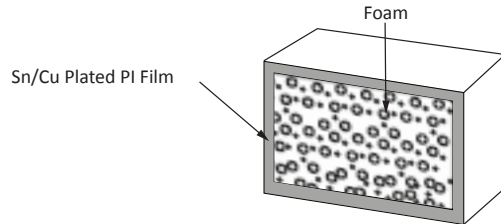
* UL file number E170327, UL designation code HB 026

**Force/Displacement/Resistance Graph of Laird
Soft SMD Contact (7 mm x 7 mm rectangle shape)**

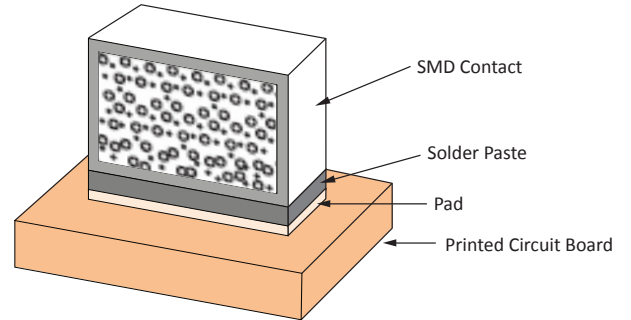


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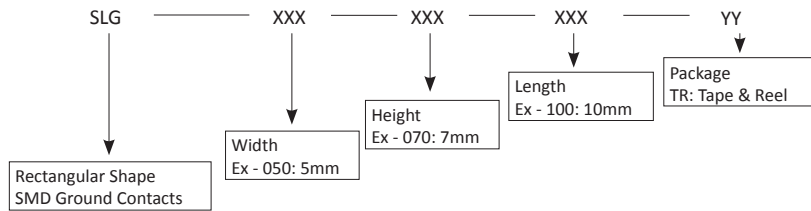
PRODUCT COMPOSITION



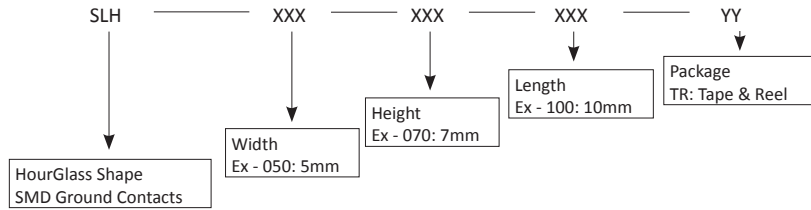
PRODUCT APPLICATION



PART NUMBER STRUCTURE



Example: "SLG-050-070-100-TR" for rectangular shape, 5mm in width, 7mm in height and 10mm length in Tape & Reel.



Example: "SLH-050-070-100-TR" for hourglass shape, 5mm in width, 7mm in height and 10mm length in Tape & Reel.

TYPICAL REFLOW CONDITIONS

| | Temperature Profile | Condition | |
|---|-------------------------|-----------------------------|----------|
| | | Temperature | Time |
| A | Preheating Stage | Room Temp. -170°C | 125 sec. |
| B | Heating / Soaking Stage | 170-217°C | 100 sec. |
| C | Reflow Stage | 217-Peak Temp. (~260°C Max) | 50 sec. |
| D | Cooling Stage | Peak Temp. - Room Temp. | >60 sec. |

Product is available in tape and reel packaging

Values presented have been determined by standard test methods and are typical values not to be used for specification purposes.

EMI-DS-FOF-SOFT-SMD 070215

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